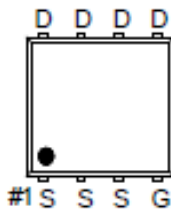


# P1203BE

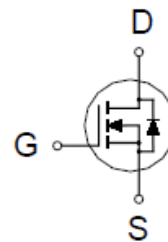
## N-Channel Enhancement Mode MOSFET

### PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
30V	12m $\Omega$ @ $V_{GS} = 10V$	9A



PDFN 3x3S



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25\text{ }^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		$V_{DS}$	30	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	
Continuous Drain Current	$T_C = 25\text{ }^\circ\text{C}$	$I_D$	36	A
	$T_C = 100\text{ }^\circ\text{C}$		22	
	$T_A = 25\text{ }^\circ\text{C}$		9	
	$T_A = 70\text{ }^\circ\text{C}$		7	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	108	
Avalanche Current		$I_{AS}$	28	
Avalanche Energy	$L = 0.1\text{mH}$	$E_{AS}$	39	mJ
Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$	$P_D$	25	W
	$T_C = 100\text{ }^\circ\text{C}$		10	
	$T_A = 25\text{ }^\circ\text{C}$		1.6	
	$T_A = 70\text{ }^\circ\text{C}$		1	
Operating Junction & Storage Temperature Range		$T_J, T_{STG}$	-55 to 150	$^\circ\text{C}$

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## N-Channel Enhancement Mode MOSFET

### THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient	$R_{\theta JA}$		75	°C / W
Junction-to-Case	$R_{\theta JC}$		3.6	

<sup>1</sup>Pulse width limited by maximum junction temperature.

### ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.3	1.8	2.5	
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 24V, V_{GS} = 0V$			1	$\mu A$
		$V_{DS} = 20V, V_{GS} = 0V, T_J = 125^\circ\text{C}$			10	
On-State Drain Current <sup>1</sup>	$I_{D(ON)}$	$V_{DS} = 5V, V_{GS} = 10V$	108			A
Drain-Source On-State Resistance <sup>1</sup>	$R_{DS(ON)}$	$V_{GS} = 4.5V, I_D = 11A$		13	17.5	m $\Omega$
		$V_{GS} = 10V, I_D = 11A$		9	12	
Forward Transconductance <sup>1</sup>	$g_{fs}$	$V_{DS} = 10V, I_D = 11A$		22		S
<b>DYNAMIC</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = 15V, f = 1\text{MHz}$		843		pF
Output Capacitance	$C_{oss}$			210		
Reverse Transfer Capacitance	$C_{rss}$			115		
Gate Resistance	$R_g$	$V_{GS} = 0V, V_{DS} = 0V, f = 1\text{MHz}$		2.1		$\Omega$
Total Gate Charge <sup>2</sup>	$Q_{g(VGS=10V)}$	$V_{DS} = 0.5V_{(BR)DSS}, I_D = 11A$		17.3		nC
	$Q_{g(VGS=4.5V)}$			9.2		
Gate-Source Charge <sup>2</sup>	$Q_{gs}$			2.7		
Gate-Drain Charge <sup>2</sup>	$Q_{gd}$			4.8		
Turn-On Delay Time <sup>2</sup>	$t_{d(on)}$		$V_{DD} = 15V,$ $I_D \cong 11A, V_{GEN} = 10V, R_G = 6\Omega$		9.8	
Rise Time <sup>2</sup>	$t_r$			12.2		
Turn-Off Delay Time <sup>2</sup>	$t_{d(off)}$			9.7		
Fall Time <sup>2</sup>	$t_f$			11.7		

## **P1203BE**

### **N-Channel Enhancement Mode MOSFET**

#### **SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS(T<sub>J</sub> = 25 °C)**

Continuous Current	I <sub>S</sub>			2.3	A
Forward Voltage <sup>1</sup>	V <sub>SD</sub>	I <sub>F</sub> = 11A, V <sub>GS</sub> = 0V		1.3	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 11A, di <sub>F</sub> /dt = 100A /μs		18	nS
Reverse Recovery Charge	Q <sub>rr</sub>			8	nC

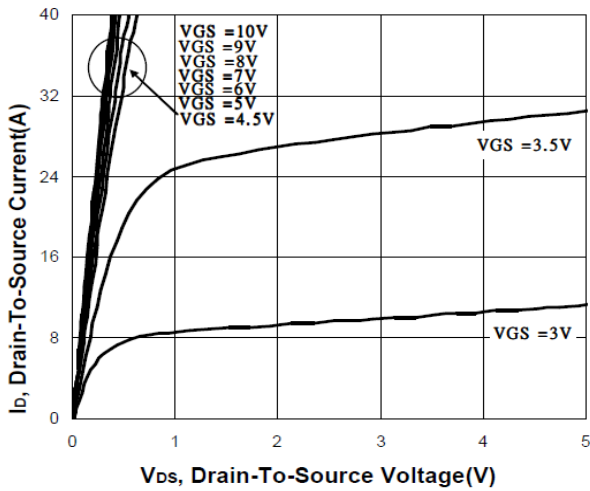
<sup>1</sup>Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

<sup>2</sup>Independent of operating temperature.

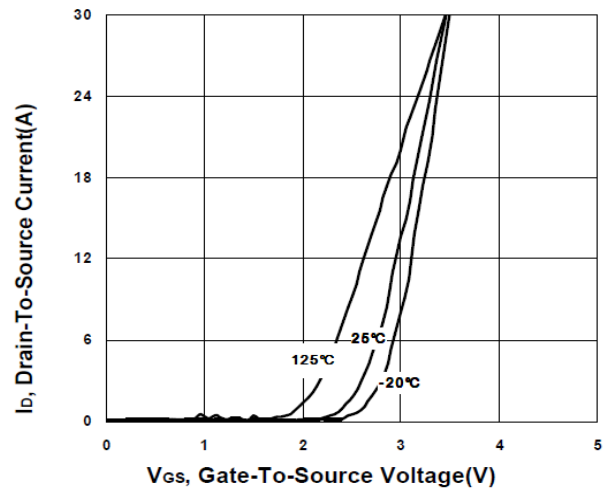
# P1203BE

## N-Channel Enhancement Mode MOSFET

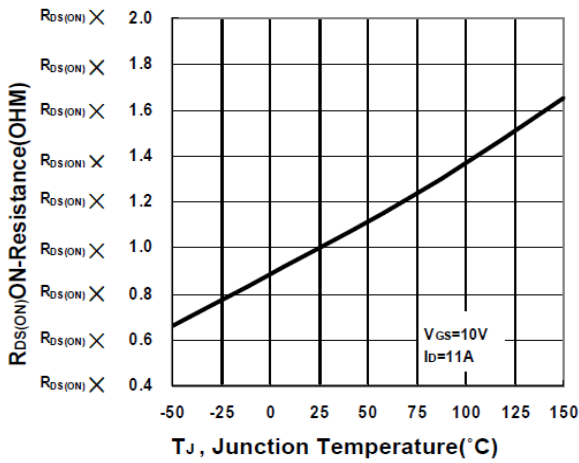
**Output Characteristics**



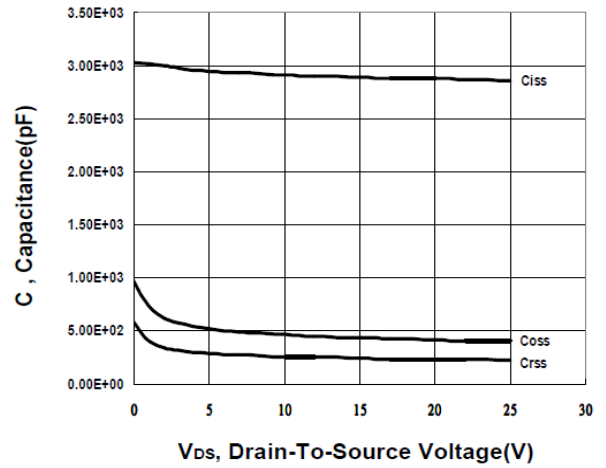
**Transfer Characteristics**



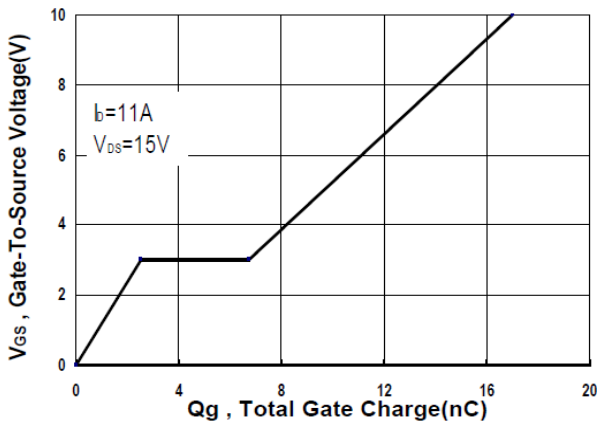
**On-Resistance VS Temperature**



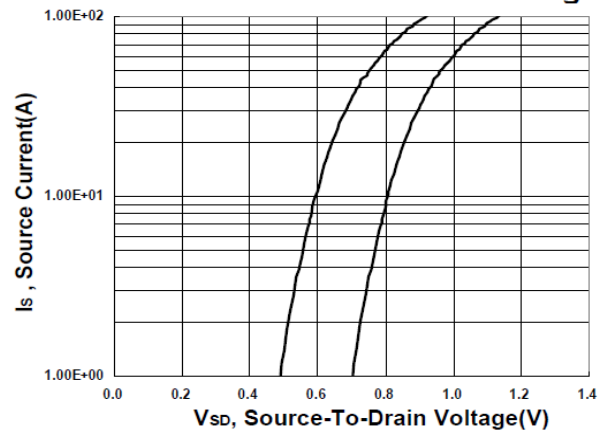
**Capacitance Characteristic**



**Gate charge Characteristics**



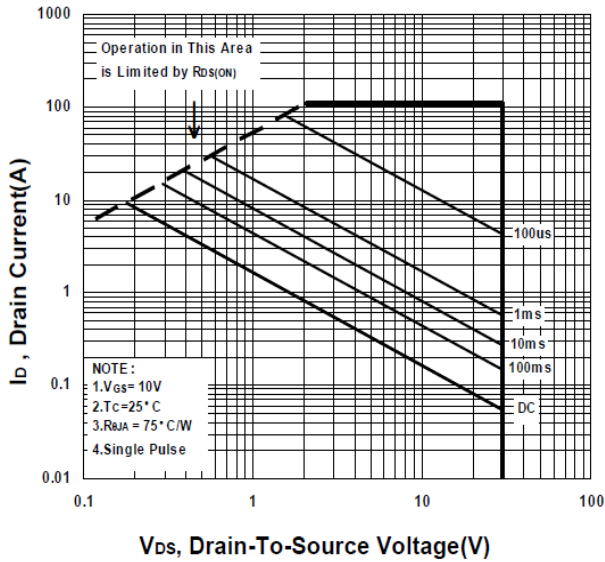
**Source-Drain Diode Forward Voltage**



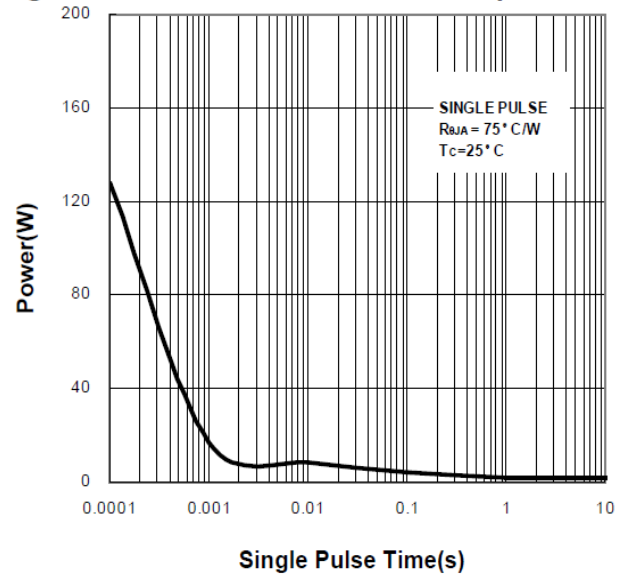
# P1203BE

## N-Channel Enhancement Mode MOSFET

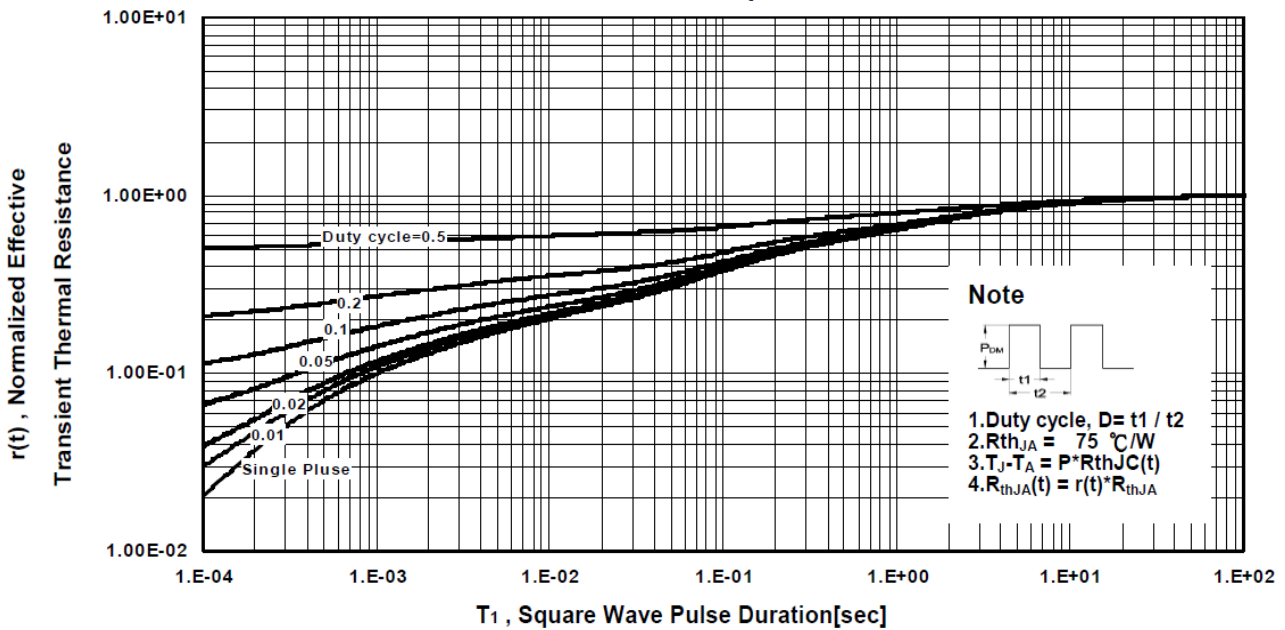
**Safe Operating Area**



**Single Pulse Maximum Power Dissipation**



**Transient Thermal Response Curve**



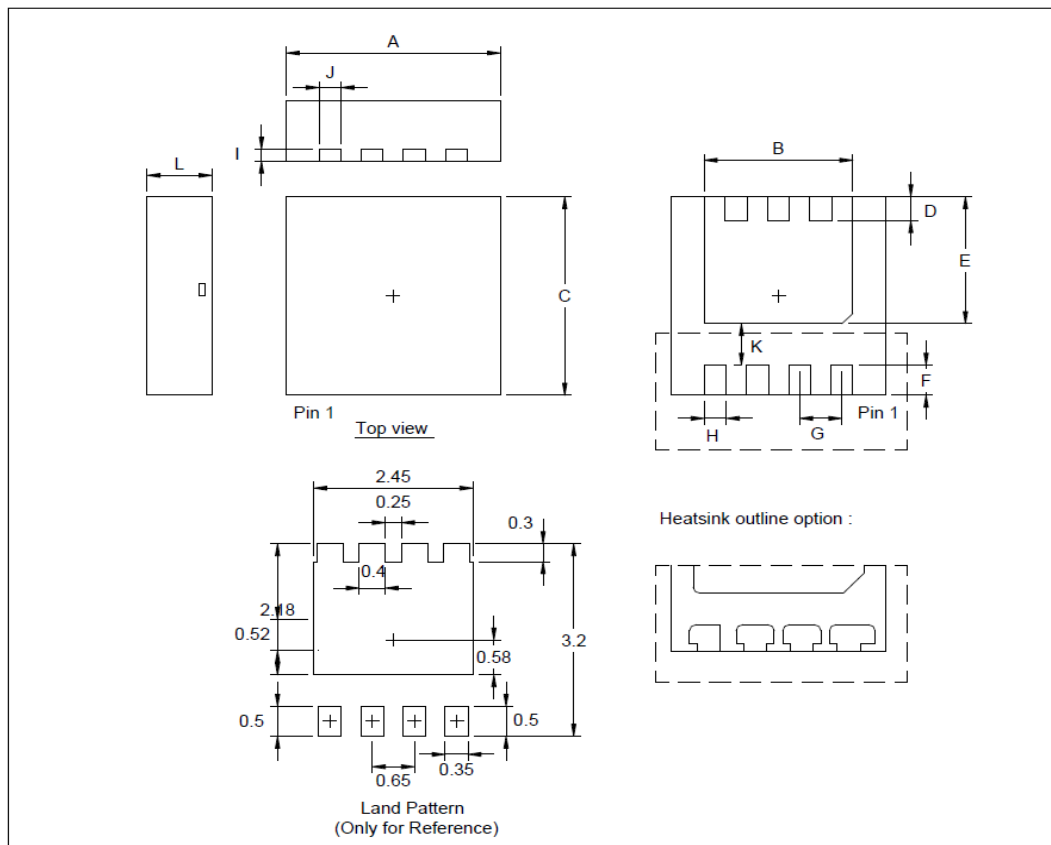
# P1203BE

## N-Channel Enhancement Mode MOSFET

### Package Dimension

### PDFN 3x3S MECHANICAL DATA

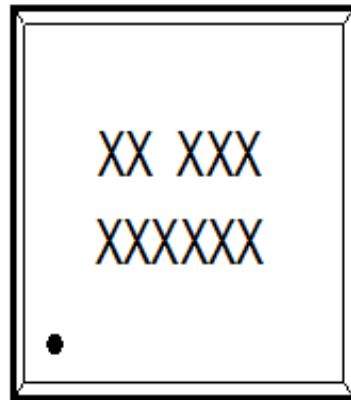
Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	2.9	3.0	3.1	I		0.20	
B	2.35	2.4	2.55	J	0.27	0.35	0.4
C	2.9	3.0	3.1	K		0.45	
D	0.32	0.4	0.45	L	0.7	0.8	0.9
E	2.0	2.1	2.2				
F	0.32	0.42	0.47				
G		0.65					
H	0.27	0.35	0.525				



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## N-Channel Enhancement Mode MOSFET

### A. Marking Information(此产品代码为: A8)

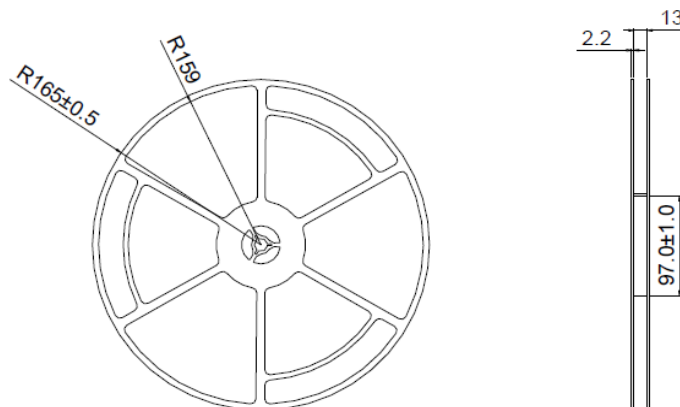
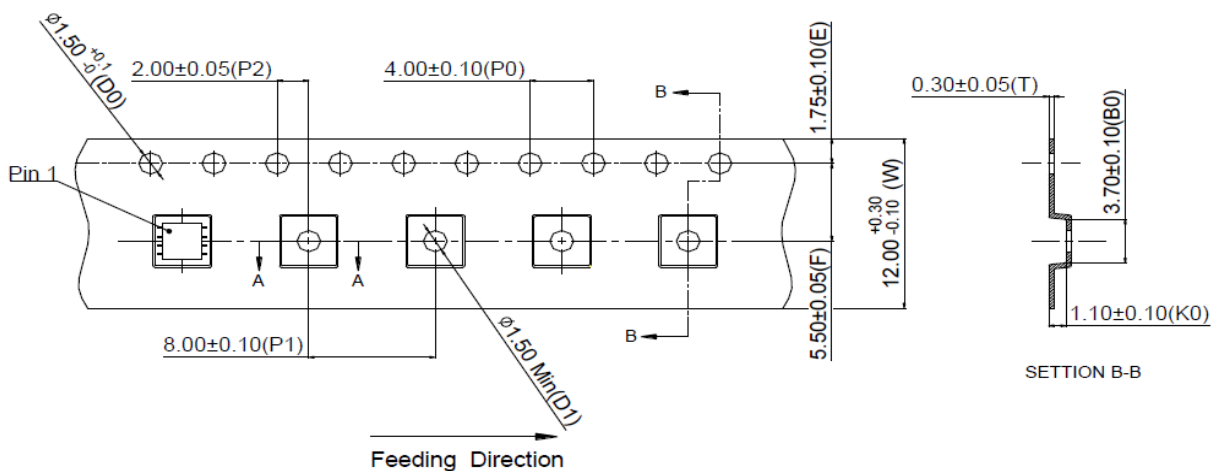


XX(前两码):产品代码

XXX

XXXXXX(后九码): LOT.NO

### B. Tape&Reel Information:5000pcs/Reel

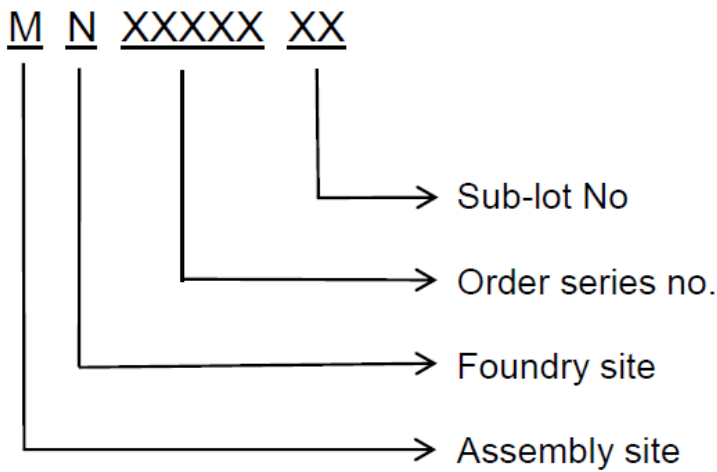


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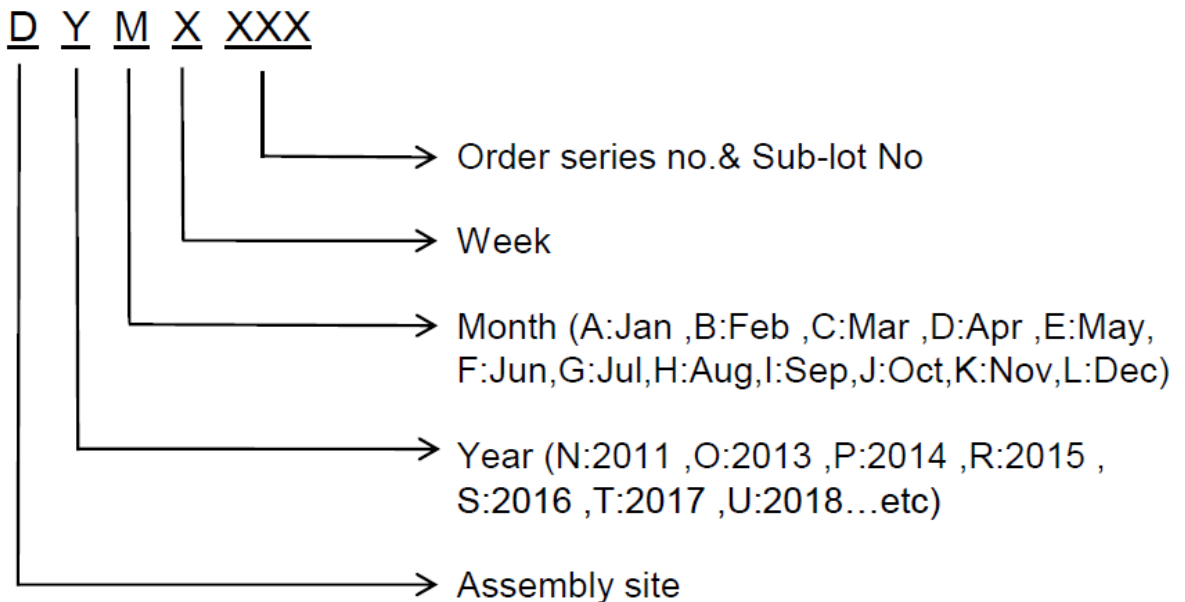
## N-Channel Enhancement Mode MOSFET

### C. Lot No.&Date Code rule

#### 1.Lot No.



#### 2.Date Code







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## N-Channel Enhancement Mode MOSFET

### D.Label rule

标签内容(Label content)



1	Label Size	30 * 90 mm
2	Font style	Times New Roman or Arial (或可区分英文"0"和数字"0", "G"和"Q"的字型即可)
3	U-NIKC	Height: 4 mm
4	Package	Height: 2 mm
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12
6	Device	Height: 3 mm (Max: 16 Digit)
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot
8	D/C	Height: 3 mm (Max: 7 Digit)
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed
10	RoHS label	 long axis: 12 mm minor axis: 6 mm bottom color: White Font color: Black Font style: Arial
11	Halogen Free label	 Diameter: 10 mm bottom color: Green Font color: Black Font style: Arial
12	Scan information	Device / Lot / D/C / QTY , Insert " / " between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least